

06-04-2002



Form PTO-1595  
(Rev. 03/01)  
OMB No. 0651-0027 (exp. 5/31/2002)

R

102110765  
COVER SHEET  
**PATENTS ONLY**

U.S. DEPARTMENT OF COMMERCE  
U.S. Patent and Trademark Office

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

## 1. Name of conveying party(ies):

- a) Sampo Semiconductor Corporation  
b) 6-4-02  
c)  
d)

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

## 2. Name and address of receiving party(ies):

Name: Amkor Technology, Inc.

Internal Address:

Street Address: 1900 South Price Road

City: Chandler State: AZ Zip: 85248-1604

Additional name(s) & address(es) attached? ☐ Yes ☒ No

## 3. Nature of conveyance:

- ☒ Assignment ☐ Merger  
☐ Security Agreement ☐ Change of Name  
☐ Other

Execution Date: May 2, 2002

## 4. Application number(s) or patent number(s):

If this document is being filed with a new application, the execution date of the application is:

A. Patent Application No.(s)

B. Patent No.(s)

5,973,407, issued October 26, 1999

Additional numbers attached? ☐ Yes ☒ No

## 5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Serge J. Hodgson  
Gunnison, McKay & Hodgson, L.L.P.

Internal Address:

Street Address: Garden West Office Plaza  
Suite 220  
1900 Garden Road

City: Monterey State: CA Zip: 93940

6. Total no. of applications and patents involved: 17. Total fee (37 CFR 3.41) . . . . . \$40.00

☒ Enclosed

☒ Authorized to charge any additional fees to deposit account

## 8. Deposit account number:

50-0553

(Attach duplicate copy of this page if paying by deposit account)

**DO NOT USE THIS SPACE**

## 9. Statement and signature.

*To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.*

Serge J. Hodgson  
Name of Person Signing

Signature

June 3, 2002  
Date

Total number of pages including cover sheet, attachments, and documents: 2

Mail documents to be recorded with required cover sheet information to:  
Commissioner of Patents & Trademarks, Box Assignments  
Washington, D.C. 20231

06/04/2002 GT0011 00000238 5973407

01 FC:561

40.00 00

**PATENT**  
**REEL: 012937 FRAME: 0131**

# Patent Assignment

For good and valuable consideration, receipt of which is hereby acknowledged, Sampo Semiconductor Corporation ("Sampo") having a place of business at, No. 1 Chung Feng Road, Kao Ping Section, Lung Tan, Taoyuan County, Taiwan, Republic of China does hereby sell, assign and transfer to Amkor Technology, Inc., a Delaware corporation, having a place of business at 1900 S. Price Road, Chandler, AZ 85248-1604, its successors and assigns, the entire right, title and interest throughout the world in U.S. Patent 5,973,407, entitled Integral Heat Spreader For Semiconductor Package issued October 26, 1999, including divisions, reissues, continuations and extensions thereof.

In witness thereof, this Patent Assignment is executed, on this 2nd day of May, 2002.



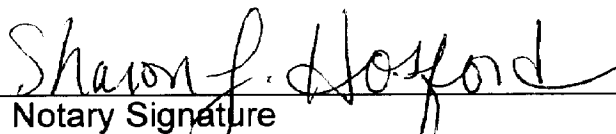
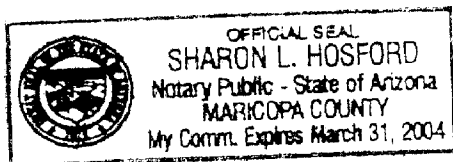
Eric Larson, Chairman  
Sampo Semiconductor Corporation

State of Arizona

ss

County of Maricopa

On this date 2nd of May, 2002, before me, Sharon L. Hosford, personally appeared Eric Larson, whose identity was proved to me on the basis of satisfactory evidence to be the person whose name is subscribed to this document, and who acknowledged that he/she signed the above/attached document.



Notary Signature

My Commission Expires: March 31, 2004